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Dual 1-of-4 FET Multiplexer / Demultiplexer

RENESAS

ADE-205-616A (Z)

Rev.1 May 2001

Description

The HD74CBT3253 is a dual 1-of-4 high-speed TTL-compatible FET multiplexer / demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

10E, 20E, S0, and S1 select the appropriate B output for the A-input data.

Features

- Minimal propagation delay through the switch.
- 5 Ω switch connection between two ports.
- TTL-compatible input levels.
- Ultra low quiescent power. -Ideally suited for notebook applications.

Function Table

Inputs

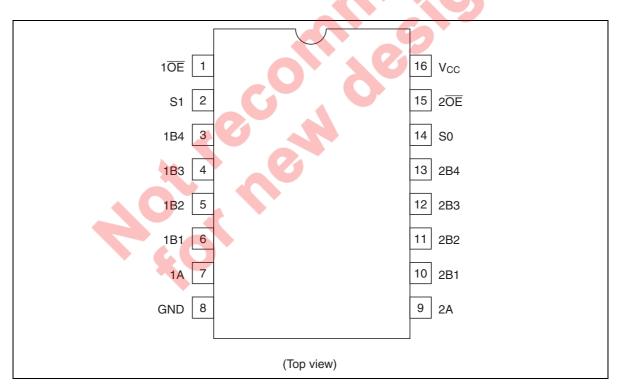
| 1 0E | 2 <mark>0E</mark> | S1 | S0 | Function |
|-----------------|-------------------|----|----|-------------------------|
| Х | Н | Х | Х | Disconnect 1A and 2A |
| Н | Х | Х | Х | Disconnect 1A and 2A |
| L | L | L | L | 1A to 1B1 and 2A to 2B1 |
| L | L | L | Н | 1A to 1B2 and 2A to 2B2 |
| L | L | Н | L | 1A to 1B3 and 2A to 2B3 |
| L | L | Н | Н | 1A to 1B4 and 2A to 2B4 |

H: High level

L: Low level

X: Immaterial

Pin Arrangement



Absolute Maximum Ratings

| Item | Symbol | Ratings | Unit | Conditions |
|---|-----------------------|-------------|------|-------------------------|
| Supply voltage range | V _{cc} | –0.5 to 7.0 | V | |
| Input voltage range ¹ | V | –0.5 to 7.0 | V | |
| Input clamp current | I _{IK} | -50 | mA | V ₁ < 0 |
| Continuous output current | I _o | 128 | mA | $V_{o} = 0$ to V_{cc} |
| Continuous current through V_{cc} or GND | I_{cc} or I_{gnD} | ±100 | mA | |
| Maximum power dissipation at Ta = 25° C (in still air) ² | P _T | 500 | mW | TSSOP |
| Storage temperature | Tstg | -65 to 150 | °C | |

Notes: The absolute maximum ratings are values which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

1. The input and output voltage ratings may be exceeded even if the input and output clamp-current ratings are observed.

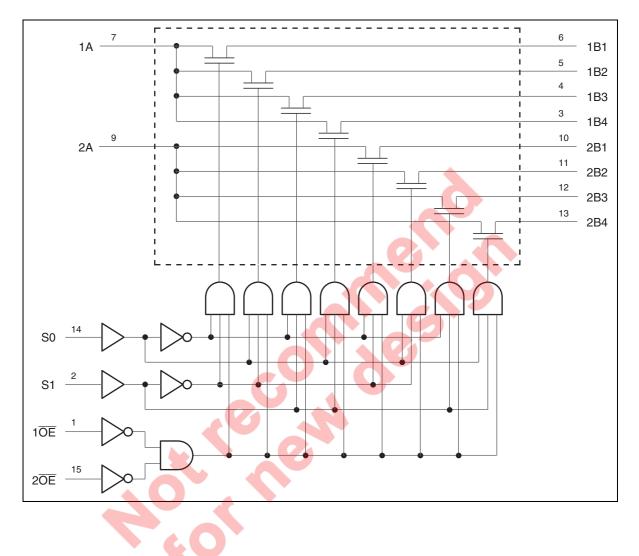
2. The maximum package power dissipation was calculated using a junction temperature of 150°C.

Recommended Operating Conditions

| Item | Symbol | Min | Max | Unit | Conditions |
|------------------------------------|------------------|-----|-----|--------|--|
| Supply voltage range | V _{cc} | 4.0 | 5.5 | V | |
| Input voltage range | Vi | 0 | 5.5 | V | |
| Output voltage range | V _{I/O} | 0 | 5.5 | V | |
| Input transition rise or fall rate | Δt / Δν | 0 | 5 | ns / V | $V_{cc} = 4.5 \text{ to } 5.5 \text{ V}$ |
| Operating free-air temperature | Та | -40 | 85 | °C | |

Note: Unused or floating inputs must be held high or low.

Block Diagram



DC Electrical Characteristics

$(Ta = -40 \text{ to } 85^{\circ}\text{C})$

| Item | Symbol | V_{cc} (V) | Min | Тур ⁺¹ | Max | Unit | Test conditions |
|--|-----------------|--------------|-----|--------|------|------|---|
| Clamp diode voltage | V _{IK} | 4.5 | | — | -1.2 | V | I _{IN} = -18 mA |
| Input voltage | V _{IH} | 4.0 to 5.5 | 2.0 | _ | _ | V | |
| | V _{IL} | 4.0 to 5.5 | | — | 0.8 | | |
| On-state switch resistance ² | R _{on} | 4.5 | _ | 5 | 7 | Ω | $V_{IN} = 0 V,$ $I_{IN} = 64 mA$ |
| | | 4.5 | _ | 5 | 7 | | $V_{IN} = 0 V,$ $I_{IN} = 30 mA$ |
| | | 4.5 | _ | 10 | 15 | 0 | $V_{IN} = 2.4 V,$ $I_{IN} = 15 mA$ |
| Input current | I _{IN} | 0 to 5.5 | | _ | ±1.0 | μA | V _{IN} = 5.5 V or GND |
| Off-state leakage current | I _{oz} | 5.5 | _ | _ | ±1.0 | μA | $0 \le A, B \le V_{cc}$ |
| Quiescent supply current | I _{cc} | 5.5 | _ | 2 | 3 | μA | $V_{IN} = V_{cc}$ or GND, $I_{o} = 0 \text{ mA}$ |
| Increase in I _{cc} per input ^{'3} | ΔI_{cc} | 5.5 | ~ | | 2.5 | mĂ | One input at 3.4 V, other inputs at V_{cc} or GND |

Notes: For condition shown as Min or Max use the appropriate values under recommended operating conditions.

1. All typical values are at $V_{cc} = 5 V$ (unless otherwise noted), Ta = 25°C.

2. Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower voltage of the two (A or B) terminals.

3. This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{cc} or GND.

Capacitance

 $(Ta = 25^{\circ}C)$

| Item | | Symbol | V _{cc} (V) | Min | Тур | Max | Unit | Test conditions |
|---------------------------|--------|--|---------------------|-----|-----|-----|------|--------------------------------------|
| Control input capacitance | | C _{IN} | 5.0 | _ | 3.5 | — | pF | $V_{IN} = 0 \text{ or } 3 \text{ V}$ |
| Input / output | A port | $\boldsymbol{C}_{_{\text{I/O}(\text{OFF})}}$ | 5.0 | _ | 15 | _ | pF | $V_{o} = 0 \text{ or } 3 \text{ V}$ |
| capacitance | B port | _ | 5.0 | | 5 | _ | | $\overline{OE} = V_{cc}$ |

Note: This parameter is determined by device characterization is not production tested.

Switching Characteristics

 $(Ta = -40 \text{ to } 85^{\circ}\text{C})$

• $V_{cc} = 4.0 V$

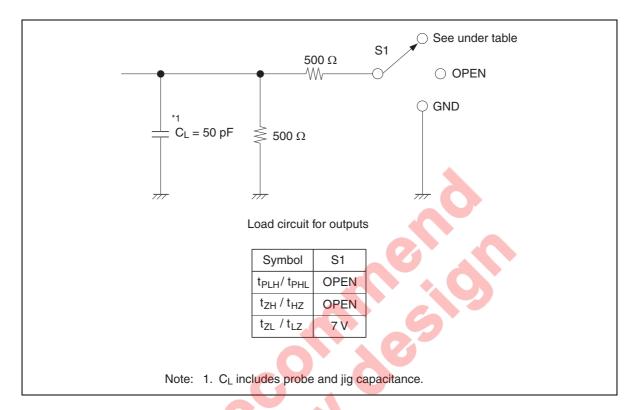
| Item | Symbol | Min | Мах | Unit | Test conditions | FROM (Input) | TO (Output) |
|--------------------------------------|--------------------------------------|-----|------|------|--|-----------------|----------------|
| Propagation delay time ^{*1} | t _{PLH} t _{PHL} | — | 0.35 | ns | $C_{L} = 50 \text{ pF}$ $R_{L} = 500 \Omega$ | A or B | B or A |
| Propagation delay time | t _{PLH} t _{PHL} | | 6.6 | ns | $C_{L} = 50 \text{ pF}$ $R_{L} = 500 \Omega$ | S | A |
| Enable time | t _{zH} t _{zL} | — | 7.1 | ns | $\begin{array}{l} C_{\scriptscriptstyle L} = 50 \text{ pF} \\ R_{\scriptscriptstyle L} = 500 \Omega \end{array}$ | S | В |
| | | _ | 7.3 | | | ŌĒ | A or B |
| Disable time | t _{HZ} t _{LZ} | | 7.9 | ns | $C_{L} = 50 \text{ pF}$ $R_{L} = 500 \Omega$ | S | В |
| | | _ | 7.3 | | | OE | A or B |

• $V_{cc} = 5.0 \pm 0.5 \text{ V}$

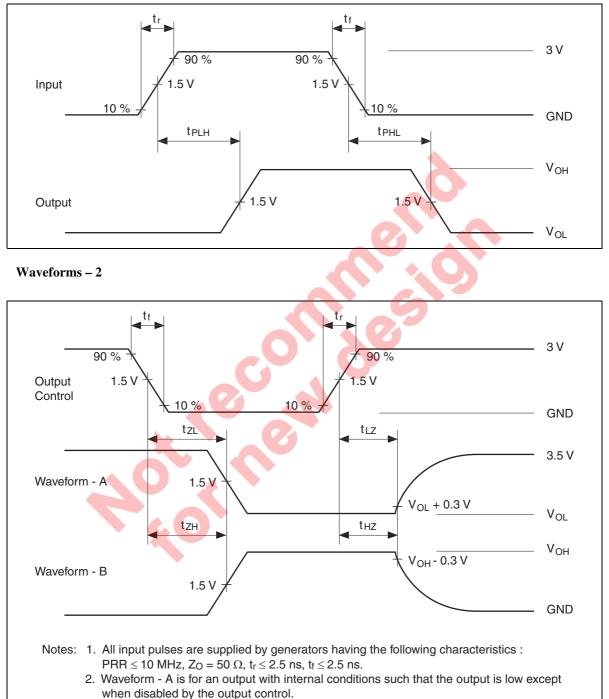
| Item | Symbol | Min | Max | Unit | Test conditions | FROM (Input) | TO (Output) |
|-------------------------------------|--------------------------------------|-----|------|------|---|-----------------|----------------|
| Propagation delay time ¹ | t _{plh} t _{phL} | .0 | 0.25 | ns | $C_L = 50 \text{ pF}$ $R_L = 500 \Omega$ | A or B | B or A |
| Propagation delay time | t _{plh} t _{phL} | 1.6 | 6.2 | ns | $C_L = 50 \text{ pF}$ $R_L = 500 \Omega$ | S | A |
| Enable time | t _{zH} t _{zL} | 1.3 | 6.3 | ns | $C_L = 50 \text{ pF}$ $R_L = 500 \Omega$ | S | В |
| | | 1.4 | 6.4 | _ | | ŌĒ | A or B |
| Disable time | t _{HZ} t _{LZ} | 1.1 | 7.4 | ns | $C_L = 50 \text{ pF}$ $R_L = 500 \Omega$ | S | В |
| | | 2.3 | 7.0 | _ | | ŌĒ | A or B |

Note: 1. The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

Test Circuit



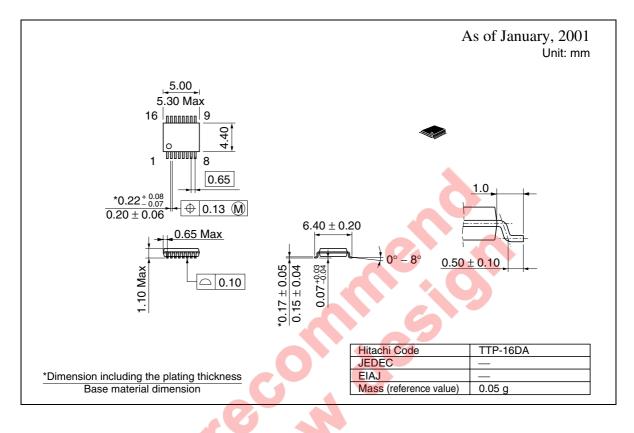
Waveforms - 1



- 3. Waveform B is for an output with internal conditions such that the output is high except when disabled by the output control.
- 4. The output are measured one at a time with one transition per measurement.

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Package Dimensions



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